

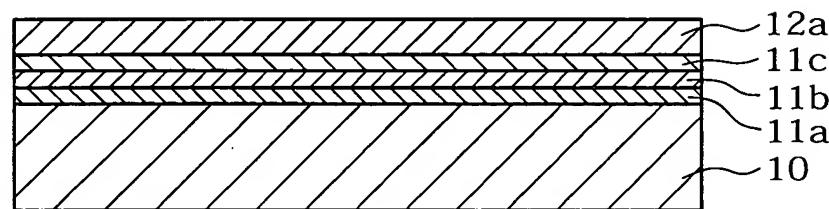
MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

Inventor: Yamanaka Hideo

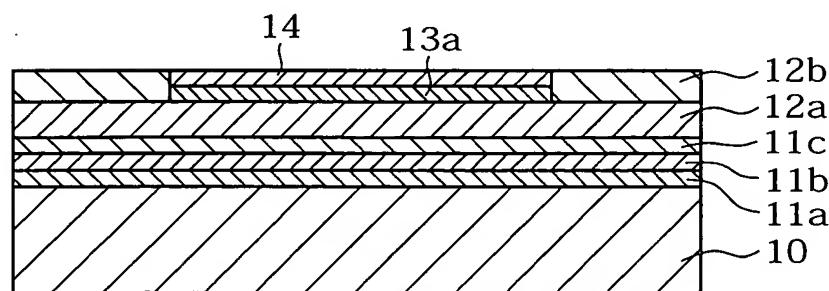
Docket No. 075834.00466

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1747

F I G. 1



F I G. 2



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

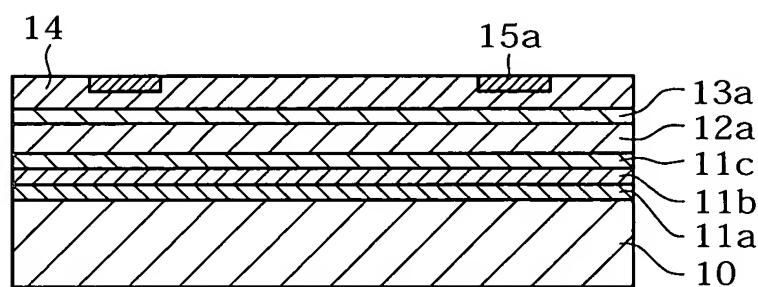
Inventor: Yamanaka Hideo

Docket No. 075834.00466

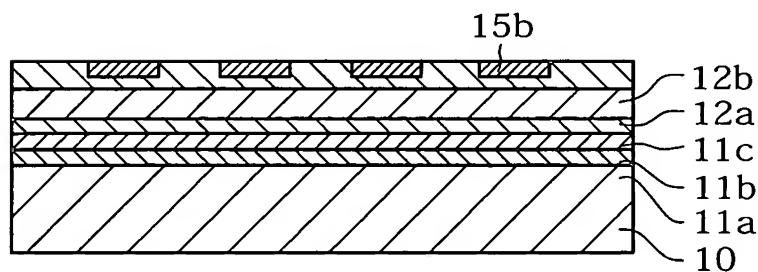
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F I G. 3 A



F I G. 3 B



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

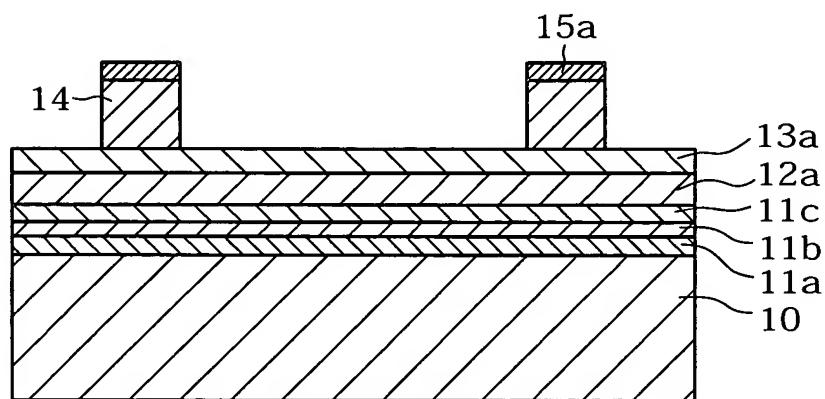
Inventor: Yamanaka Hideo

Docket No. 075834.00466

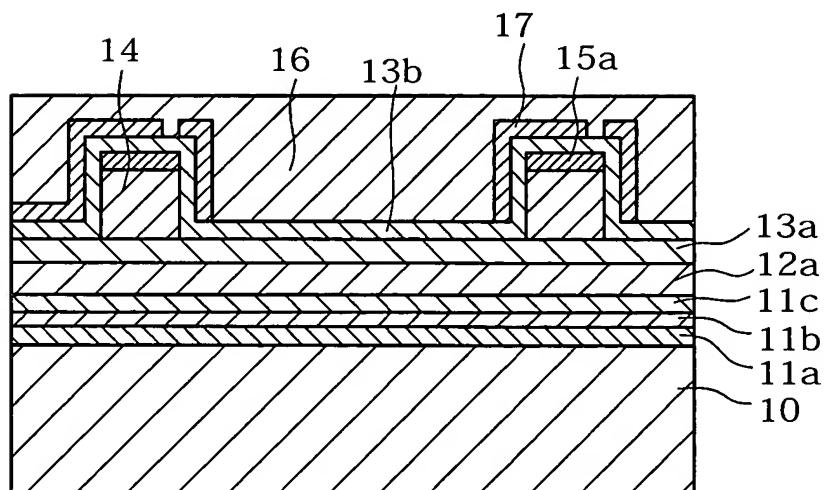
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F I G. 4



F I G. 5



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

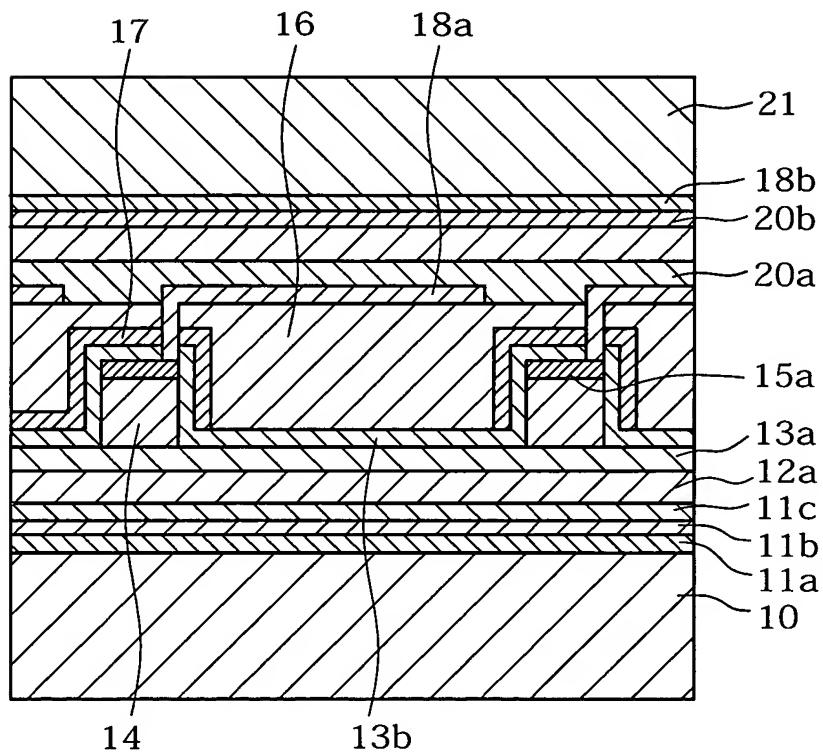
Inventor: Yamanaka Hideo

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F I G. 6



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

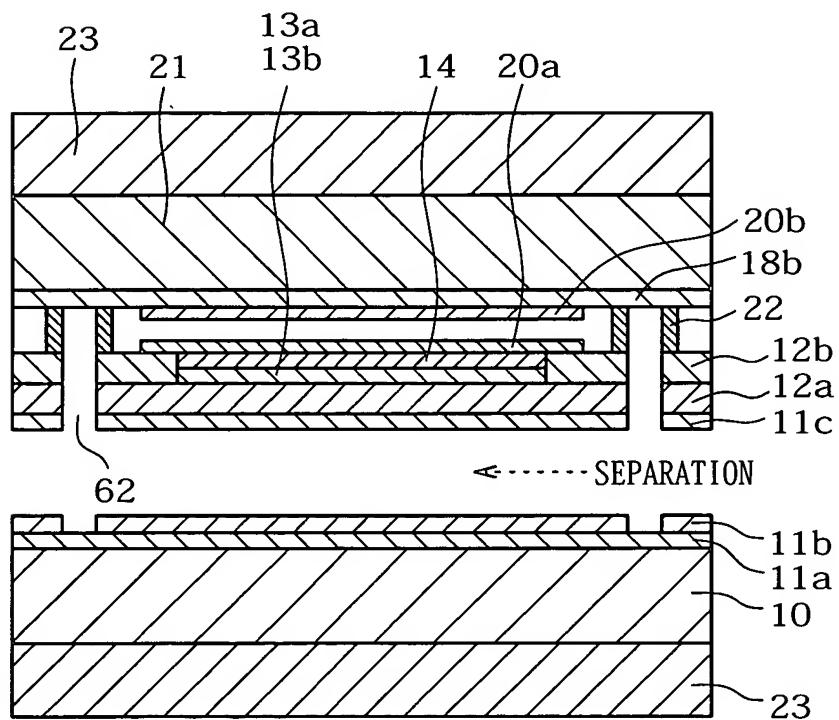
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F I G. 7



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

Inventor: Yamanaka Hideo

Docket No. 075834.00466

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FIG. 8 A

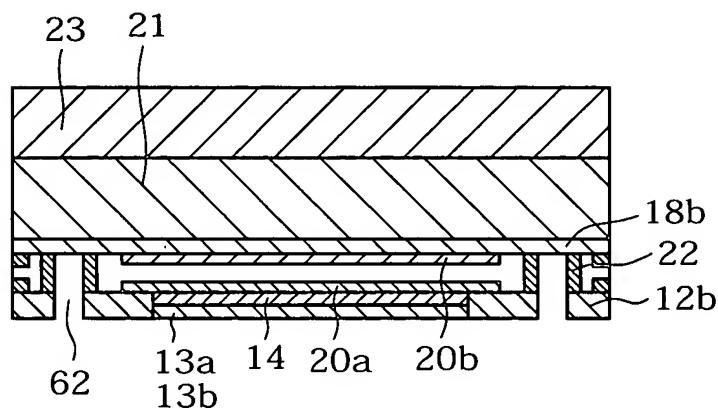
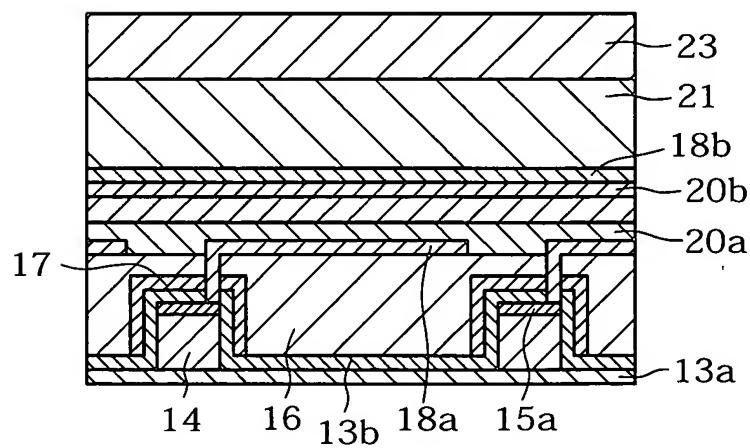


FIG. 8 B



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

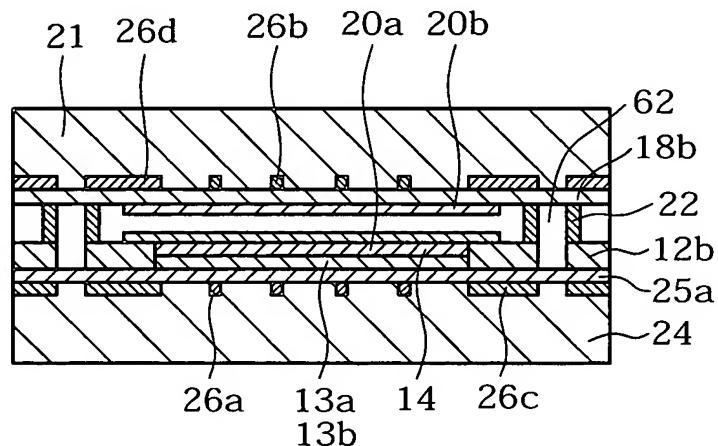
Inventor: Yamanaka Hideo

Docket No. 075834.00466

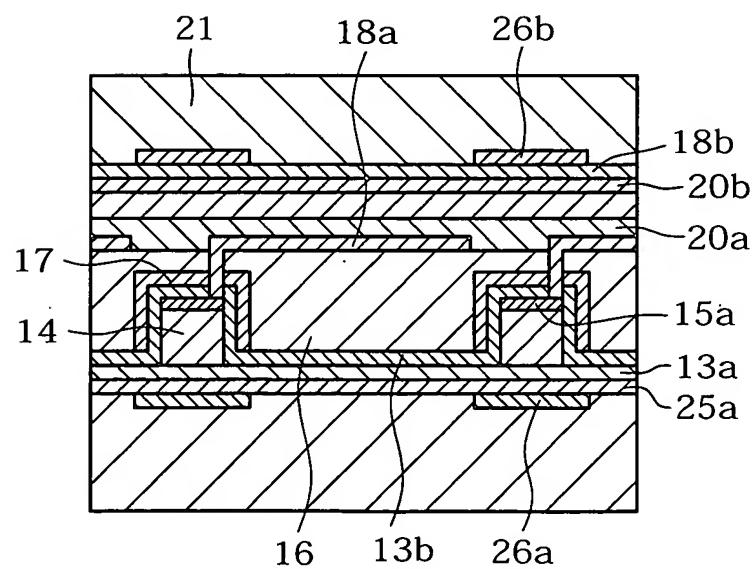
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F I G. 9 A



F I G. 9 B



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

Inventor: Yamanaka Hideo

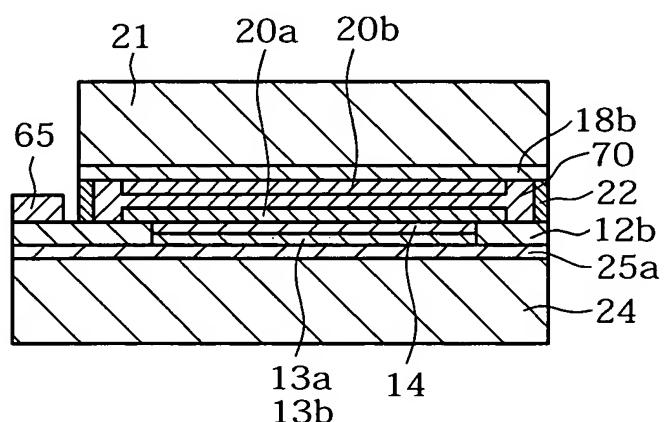
Docket No. 075834.00466

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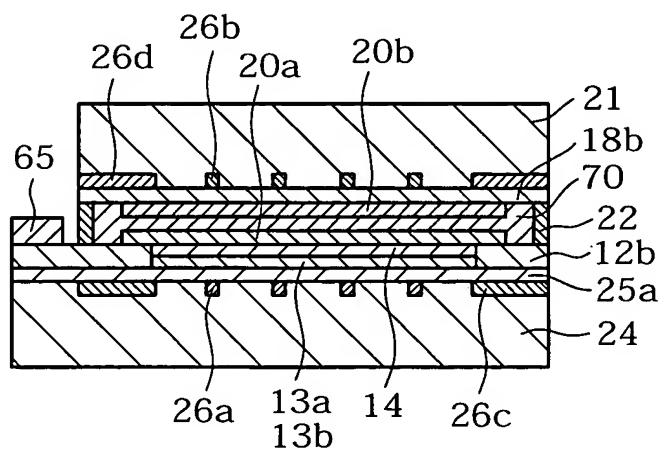
F I G. 10 A

(a) WITHOUT A LIGHT-SHIELDING FILM



F I G. 10 B

(a) WITH A LIGHT-SHIELDING FILM



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

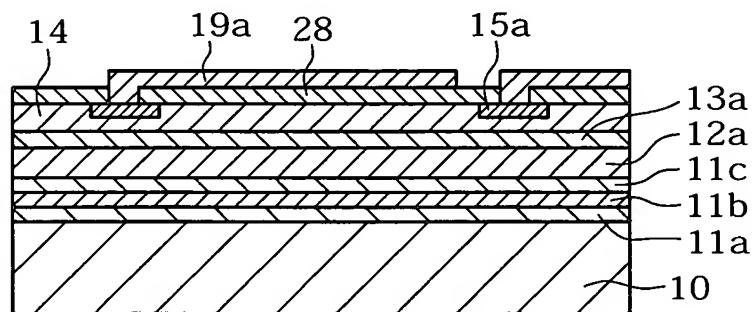
Inventor: Yamanaka Hideo

Docket No. 075834.00466

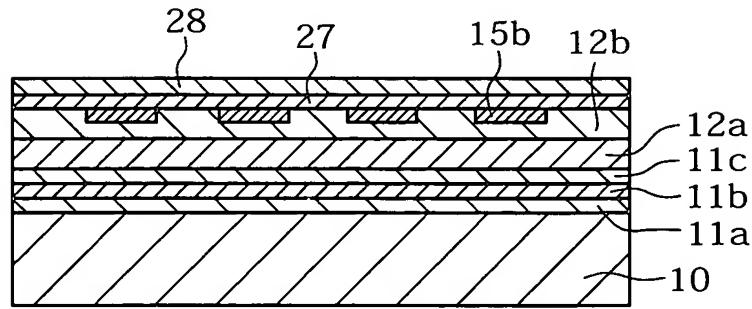
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F I G. 11 A



F I G. 11 B



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

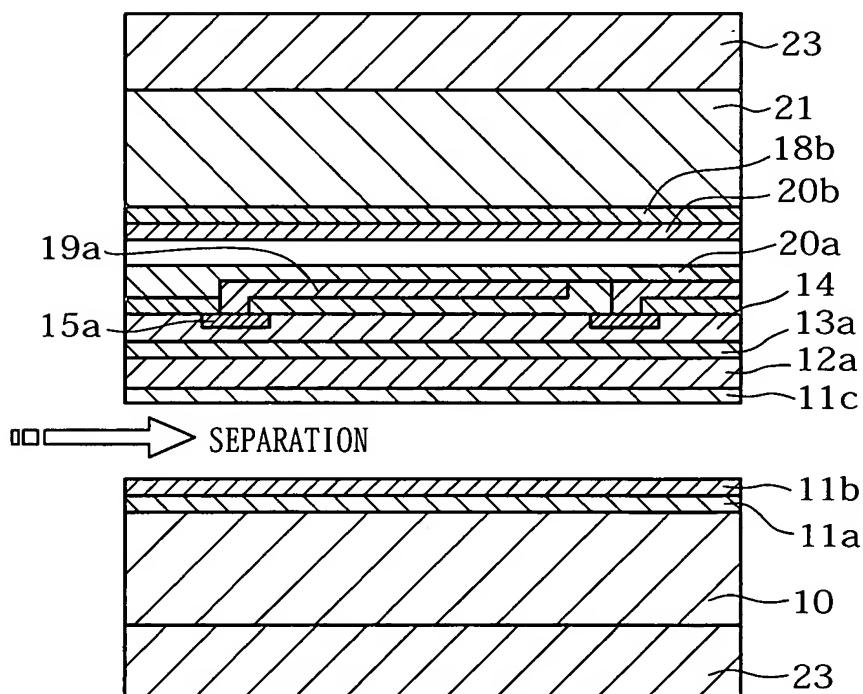
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F I G. 1 2



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Inventor: Yamanaka Hideo

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FIG. 13 A

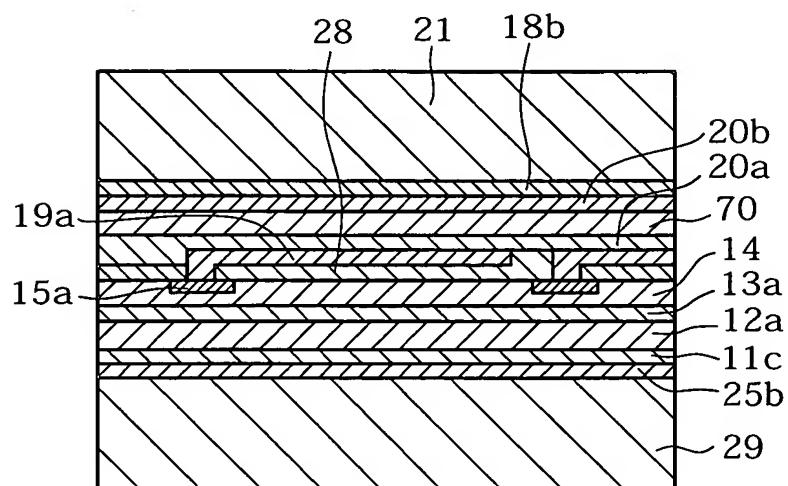
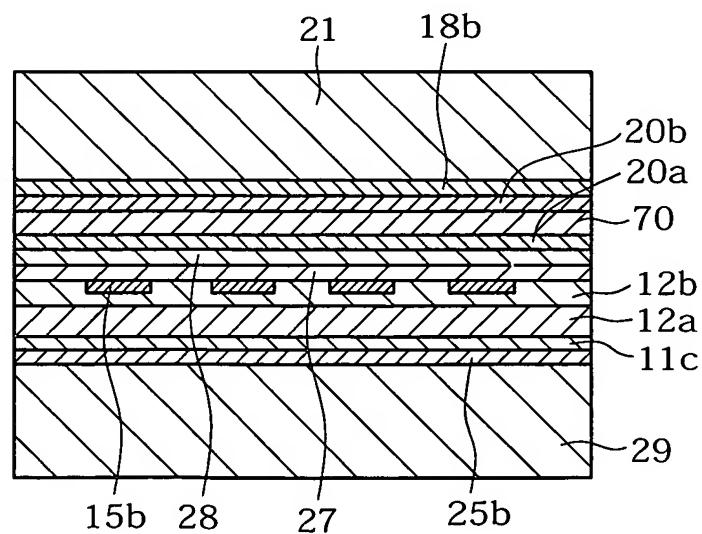


FIG. 13 B



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

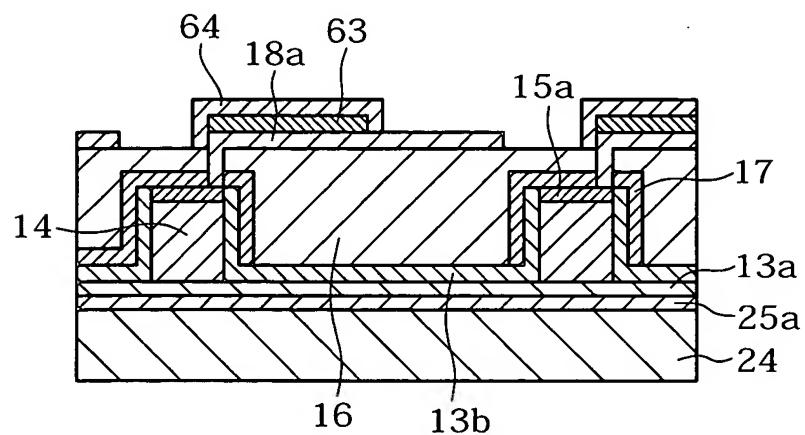
Inventor: Yamanaka Hideo

Docket No. 075834.00466

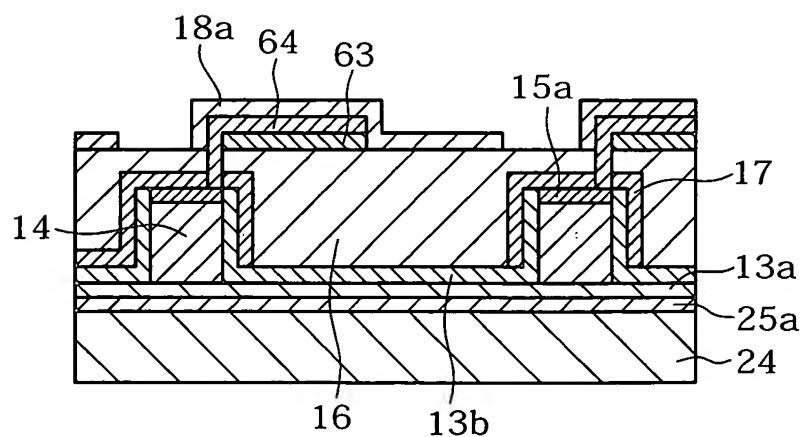
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F I G. 14 A



F I G. 14 B



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

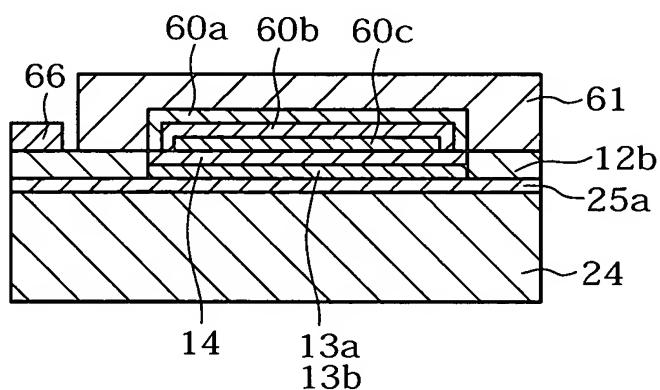
Inventor: Yamanaka Hideo

Docket No. 075834.00466

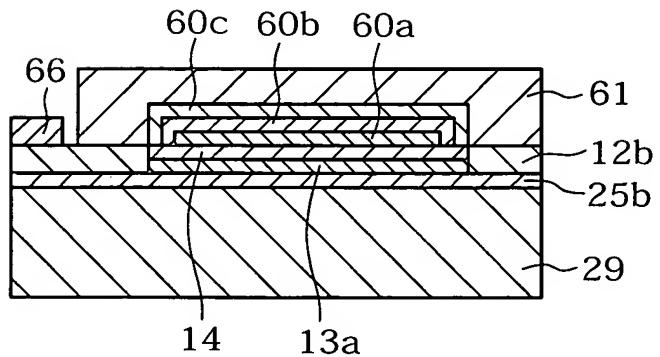
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F I G. 15



F I G. 16



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

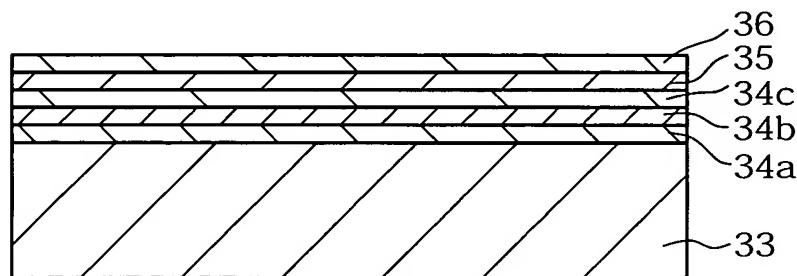
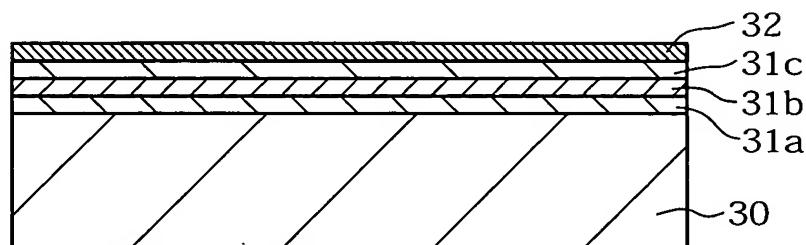
Inventor: Yamanaka Hideo

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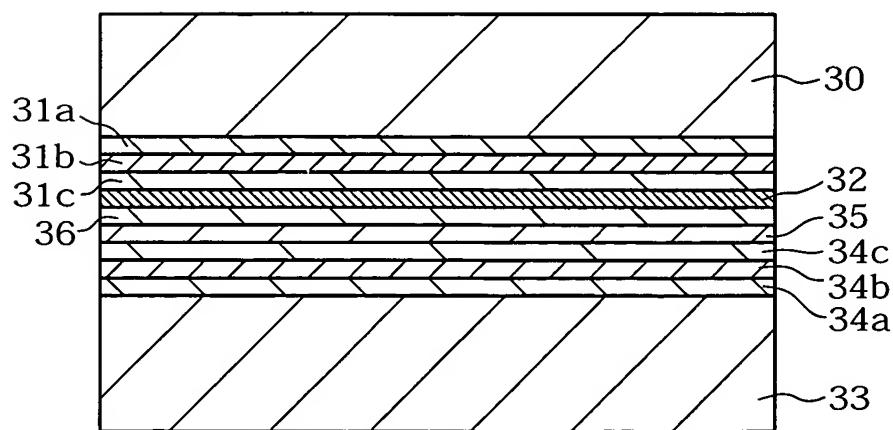
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F I G. 1 7



F I G. 1 8



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

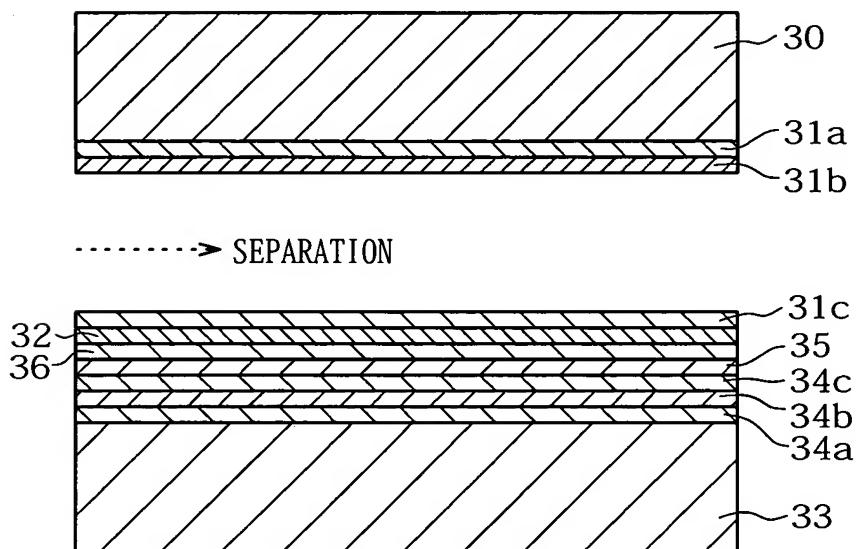
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F I G. 1 9



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

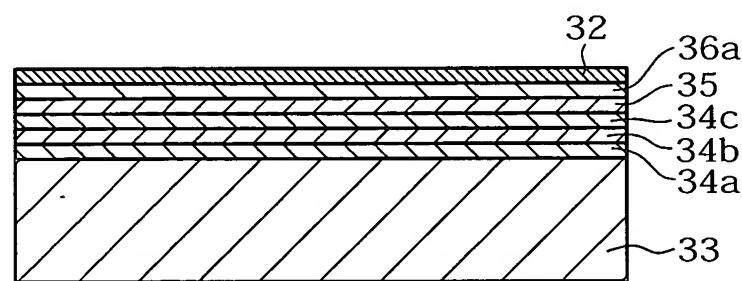
Inventor: Yamanaka Hideo

Docket No. 075834.00466

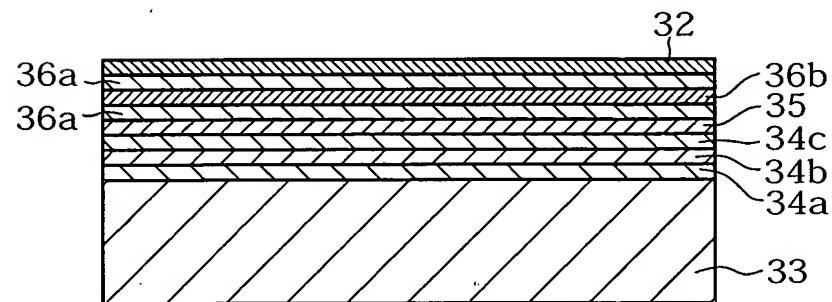
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F I G. 20 A



F I G. 20 B



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

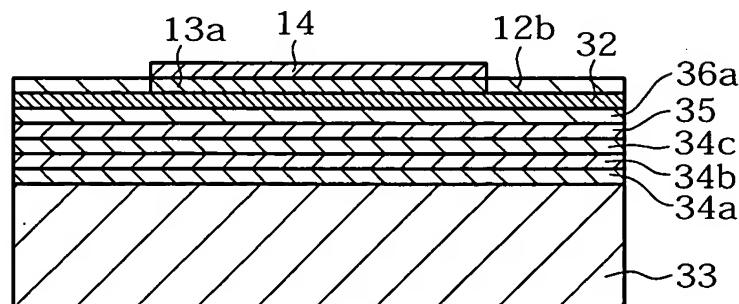
Inventor: Yamanaka Hideo

Docket No. 075834.00466

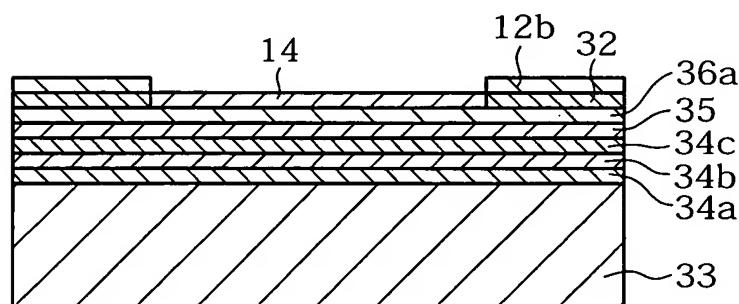
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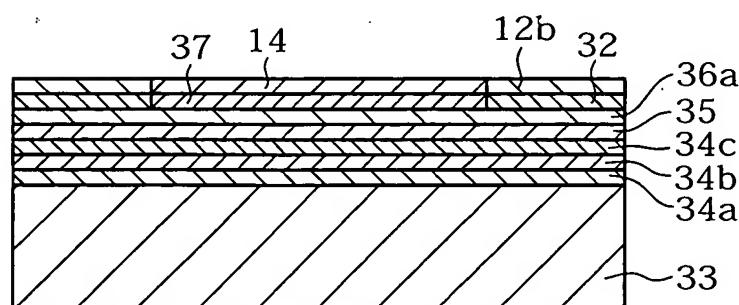
F I G. 2 1 A



F I G. 2 1 B



F I G. 2 1 C



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

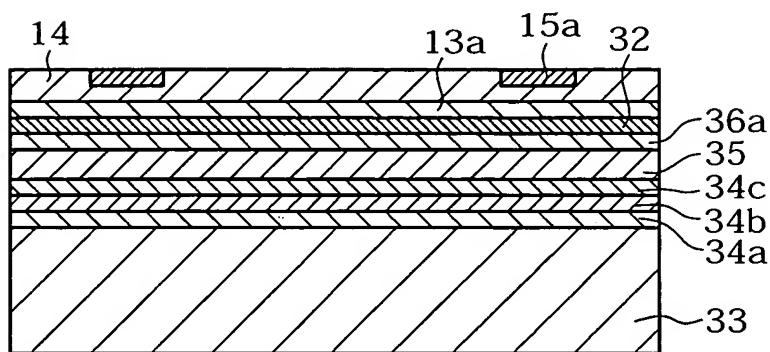
Inventor: Yamanaka Hideo

Docket No. 075834.00466

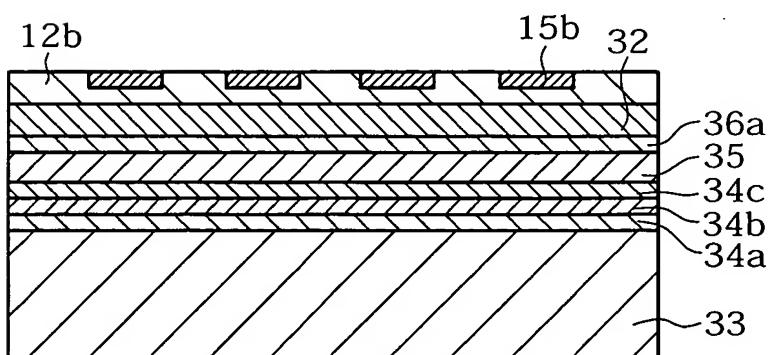
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F I G. 22 A



F I G. 22 B



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

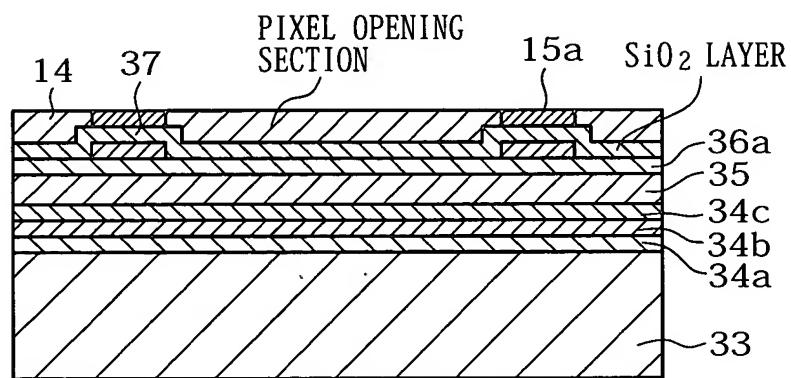
Inventor: Yamanaka Hideo

Docket No. 075834.00466

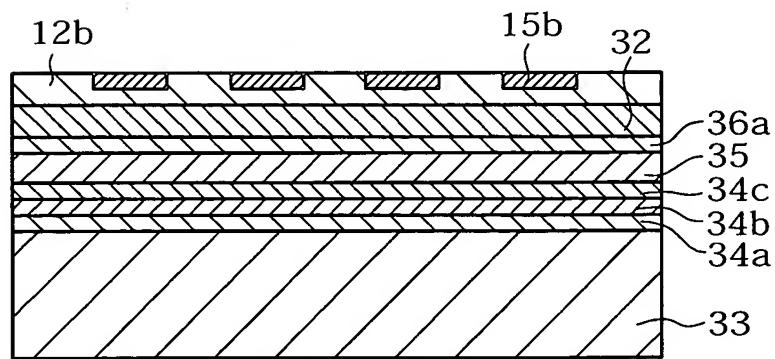
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F I G. 23 A



F I G. 23 B



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

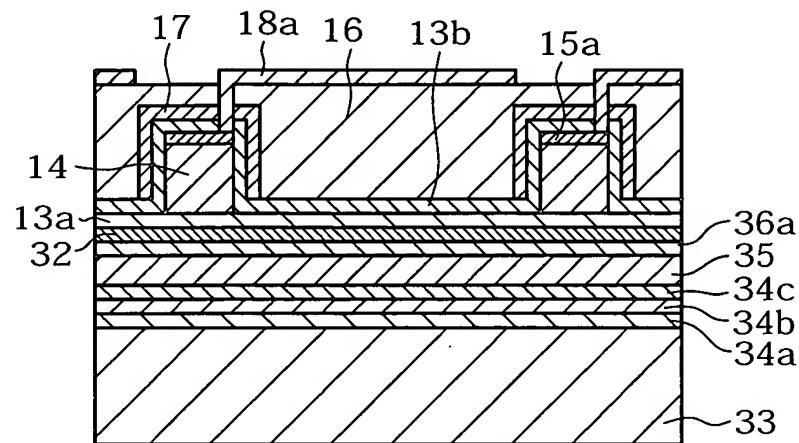
Inventor: Yamanaka Hideo

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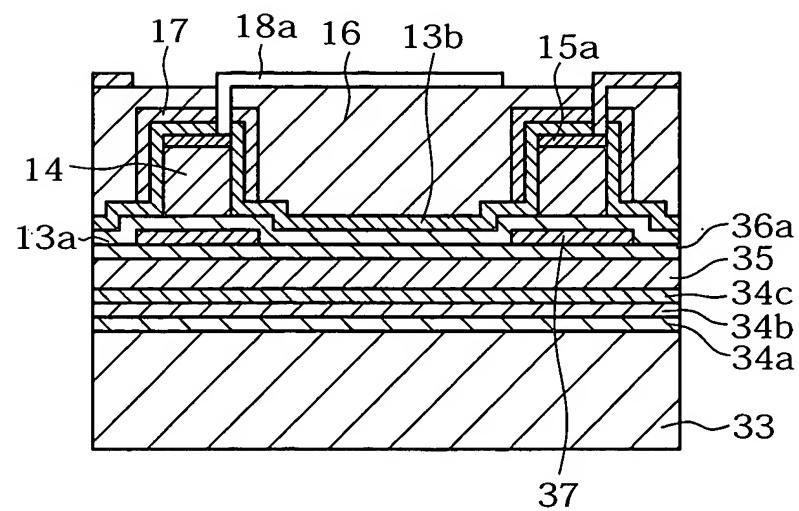
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F I G. 24 A



F I G. 24 B



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

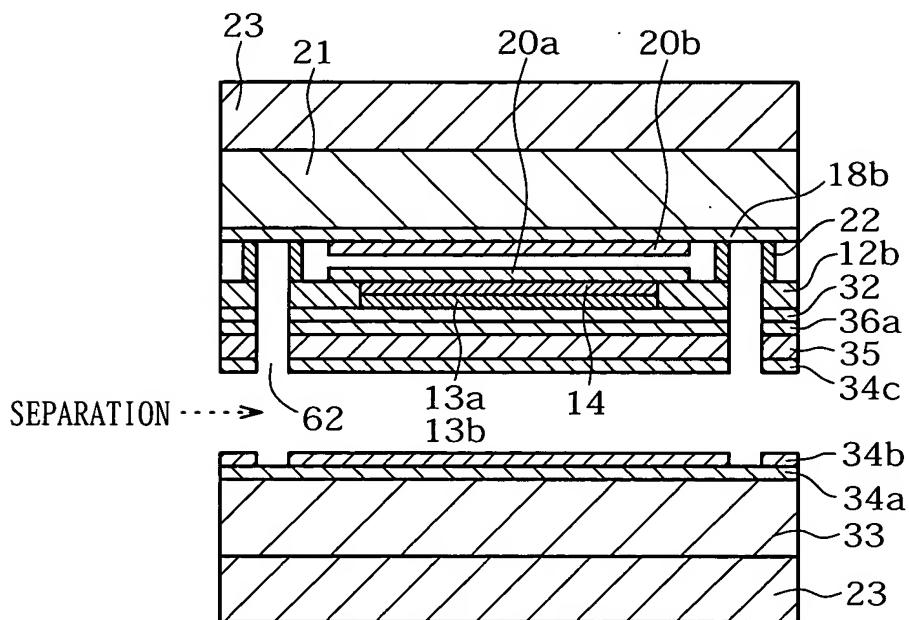
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F I G. 2 5



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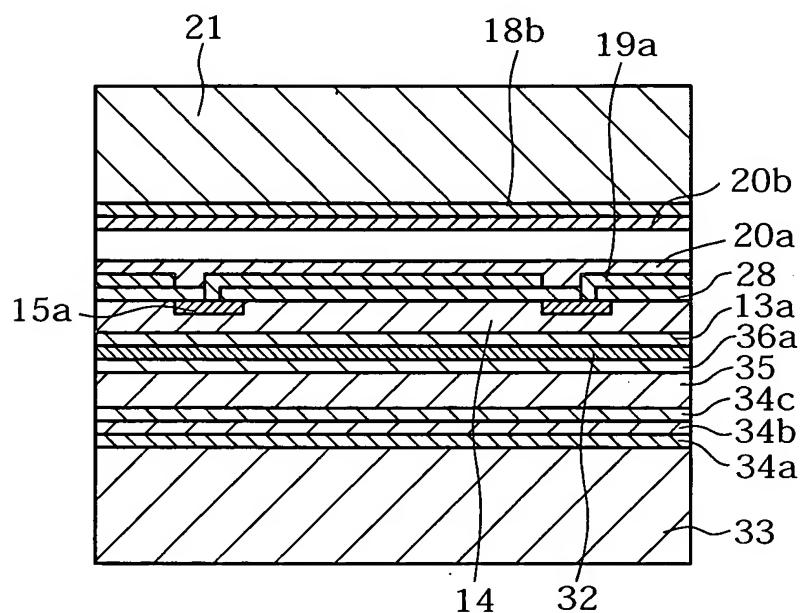
Inventor: Yamanaka Hideo

Docket No. 075834.00466

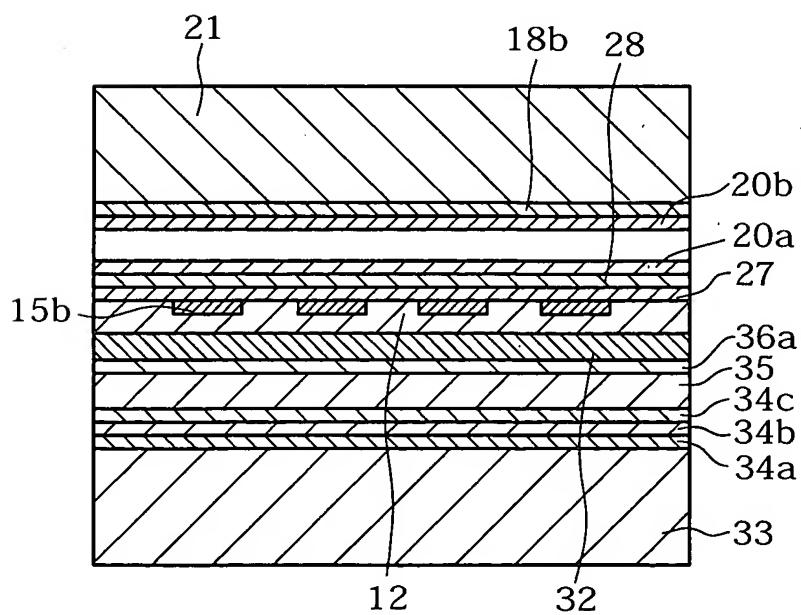
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F I G. 26 A



F I G. 26 B



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

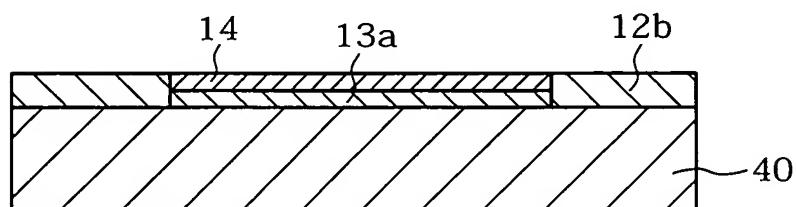
Inventor: Yamanaka Hideo

Docket No. 075834.00466

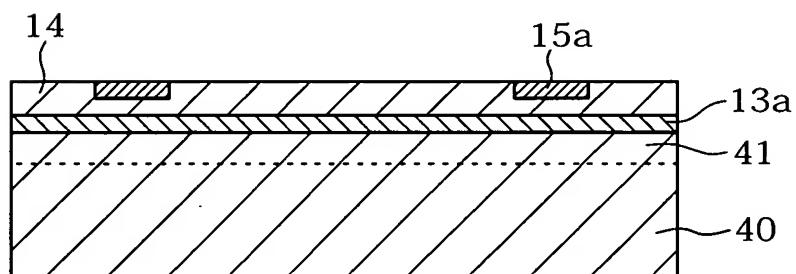
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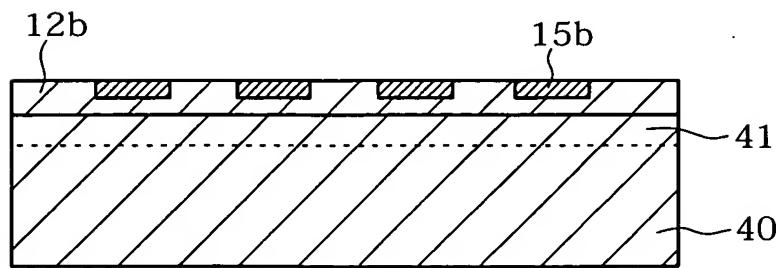
F I G. 2 7



F I G. 2 8 A



F I G. 2 8 B



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

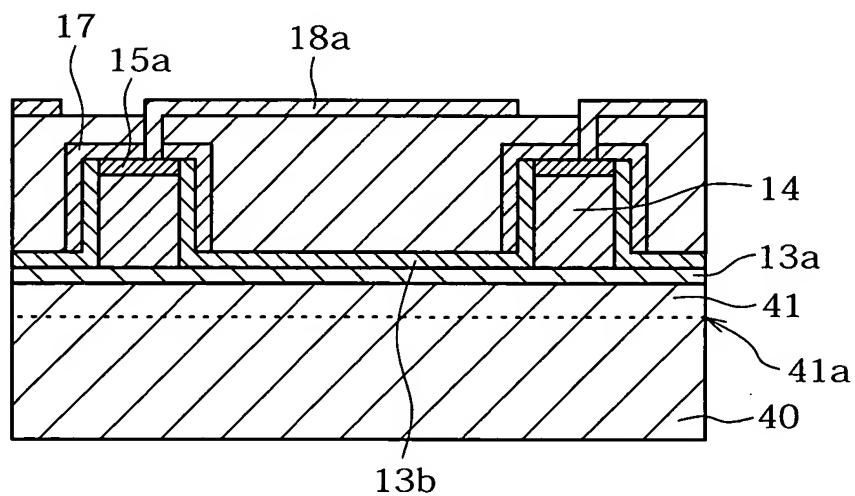
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F I G. 29



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

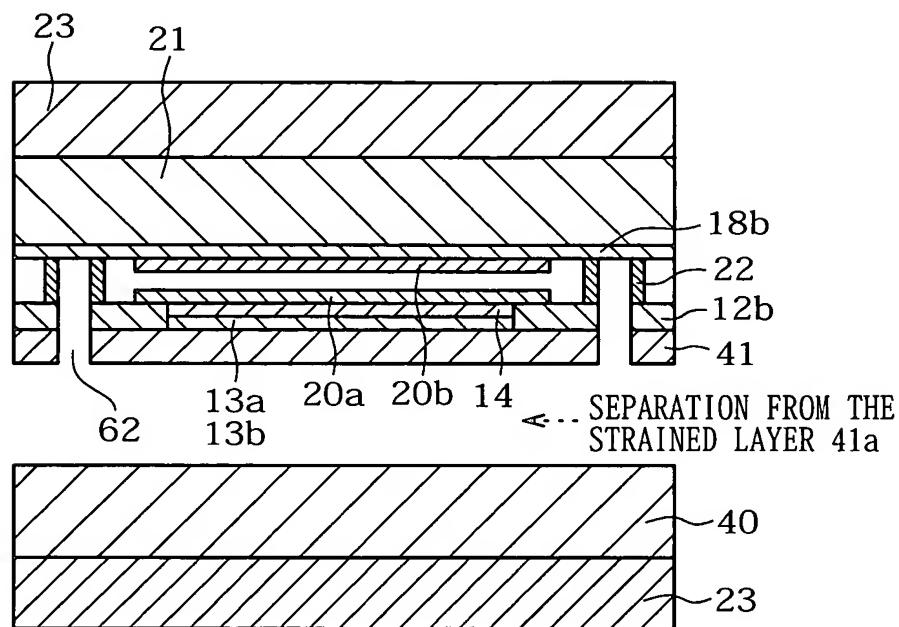
Inventor: Yamanaka Hideo

Docket No. 075834.00466

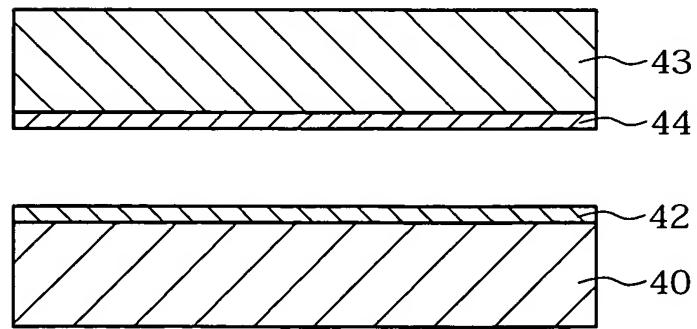
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F I G. 3 0



F I G. 3 1



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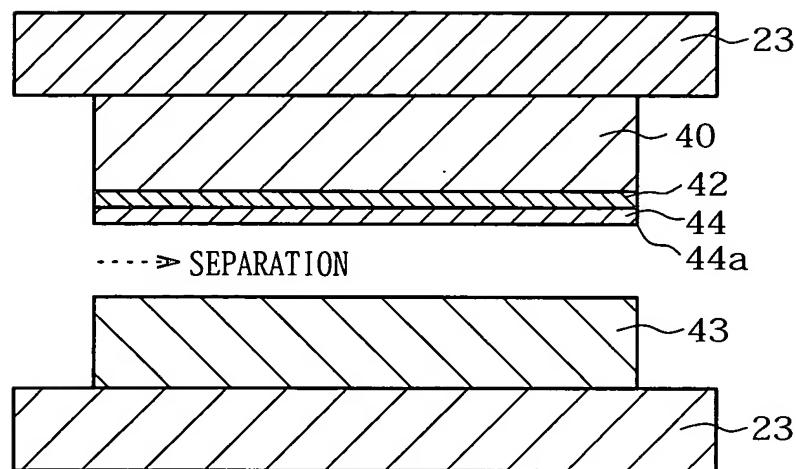
Inventor: Yamanaka Hideo

Docket No. 075834.00466

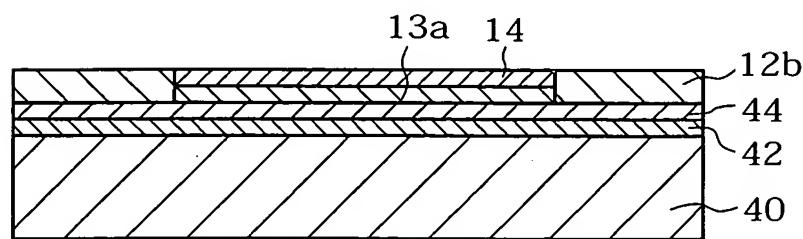
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F I G. 3 2



F I G. 3 3



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

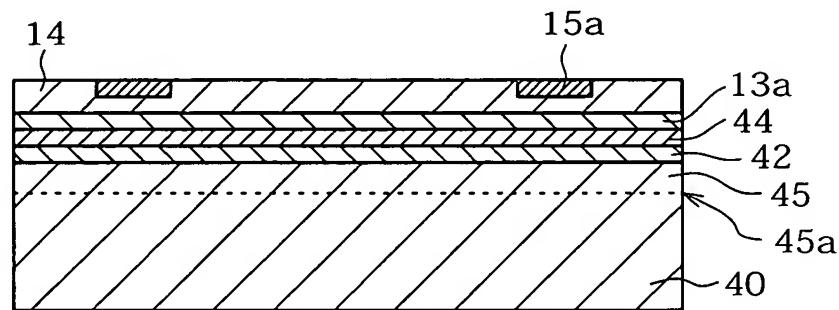
Inventor: Yamanaka Hideo

Docket No. 075834.00466

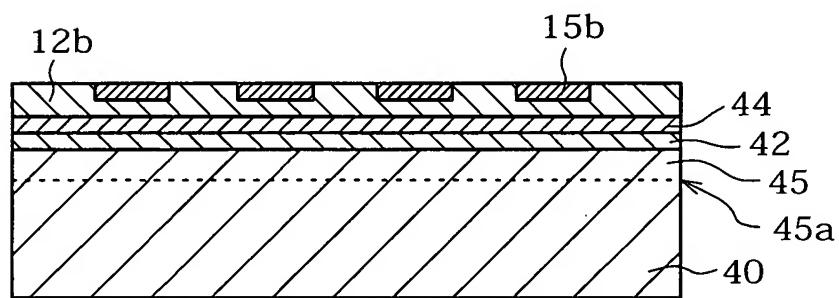
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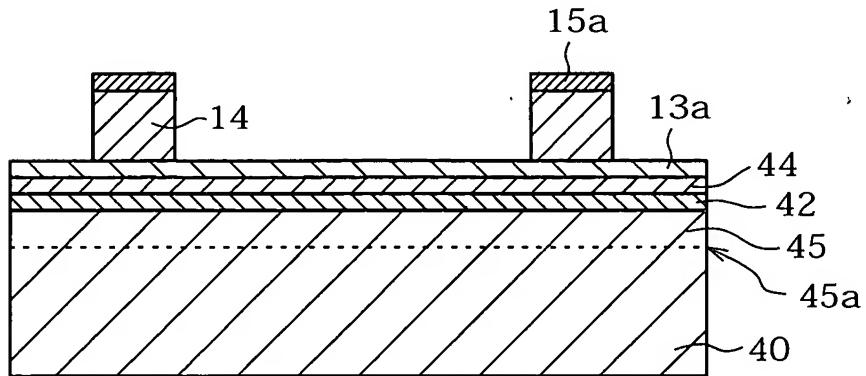
F I G. 3 4 A



F I G. 3 4 B



F I G. 3 5



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

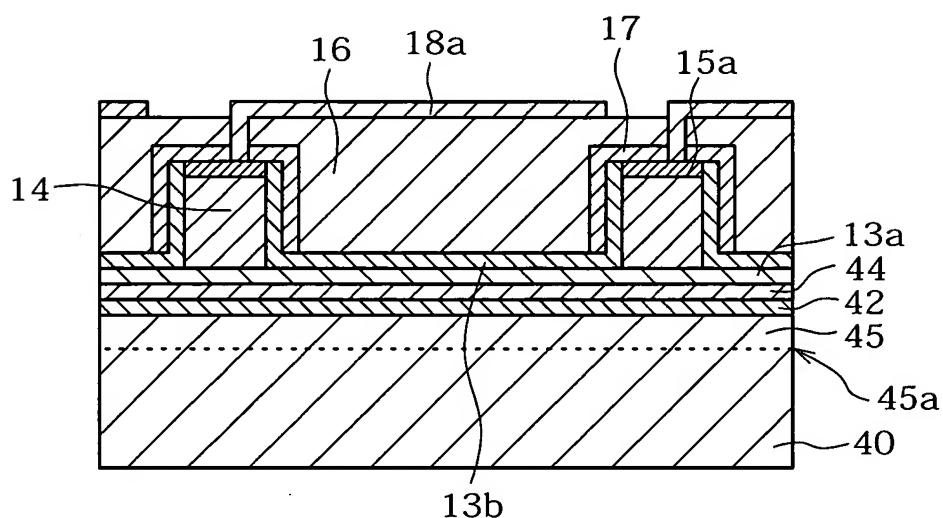
Inventor: Yamanaka Hideo

Docket No. 075834.00466

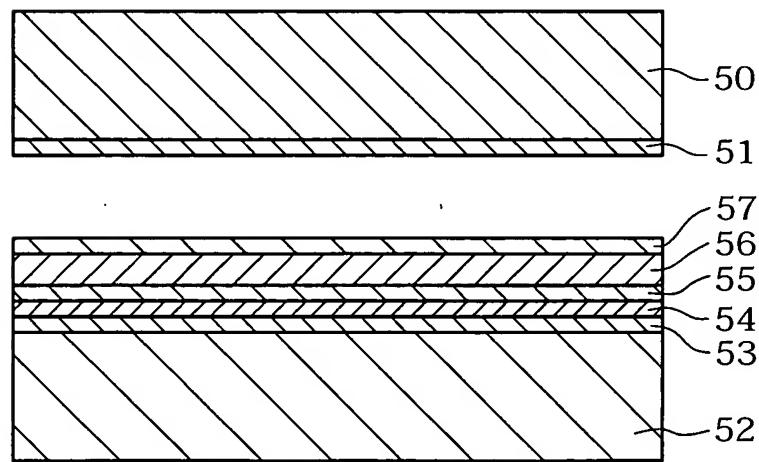
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F I G. 3 6



F I G. 3 7



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

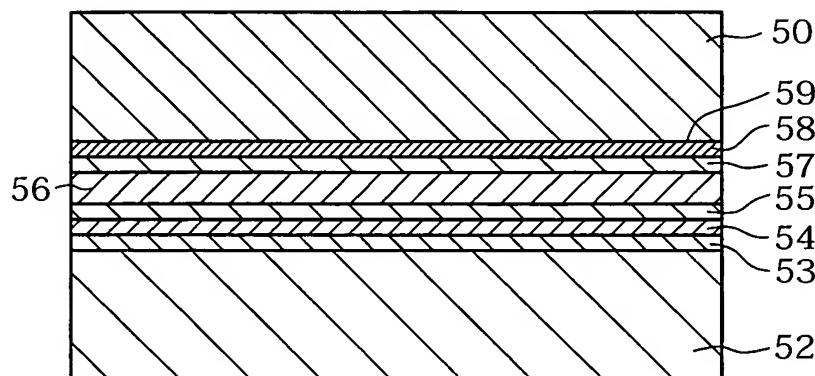
Inventor: Yamanaka Hideo

Docket No. 075834.00466

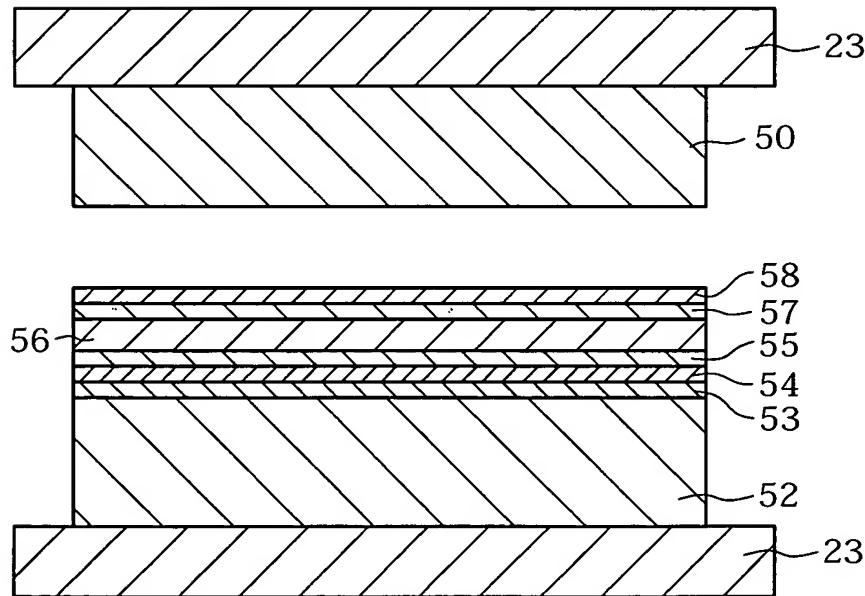
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F I G. 3 8



F I G. 3 9



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

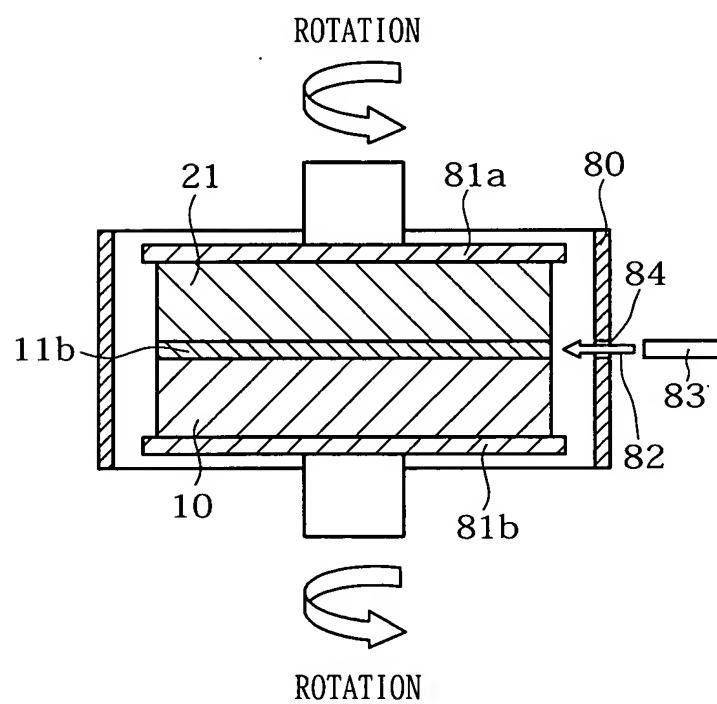
Inventor: Yamanaka Hideo

Docket No. 075834.00466

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F I G. 4 0



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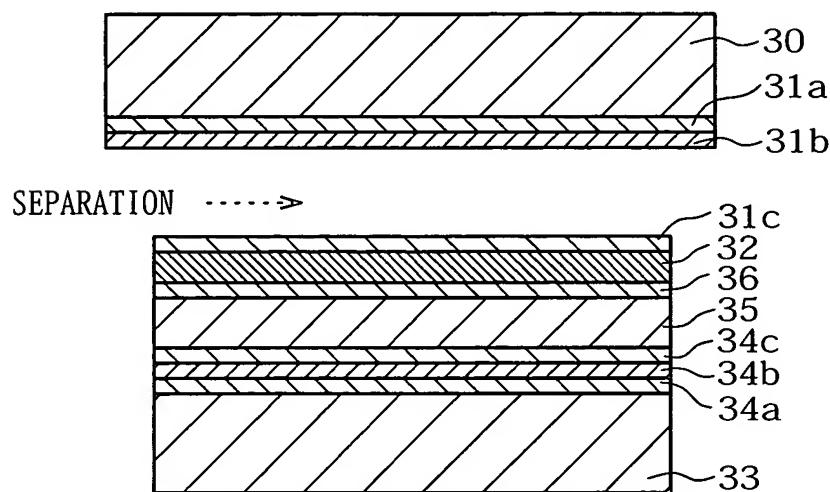
Inventor: Yamanaka Hideo

Docket No. 075834.00466

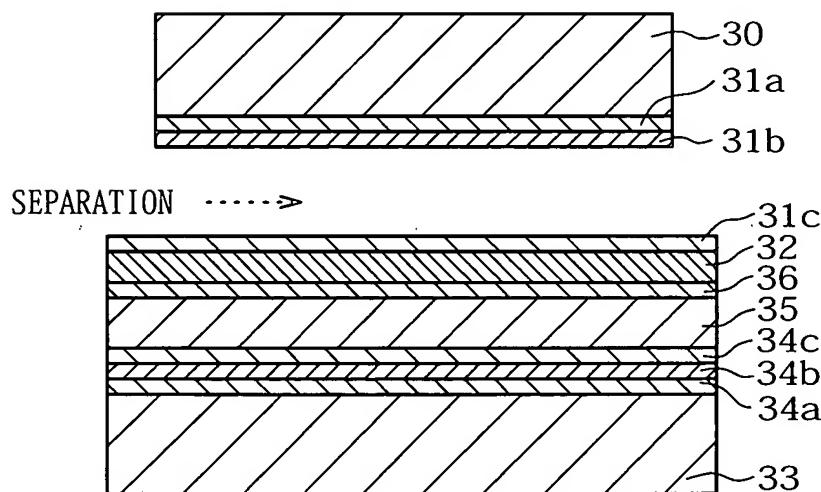
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F I G. 41 A



F I G. 41 B



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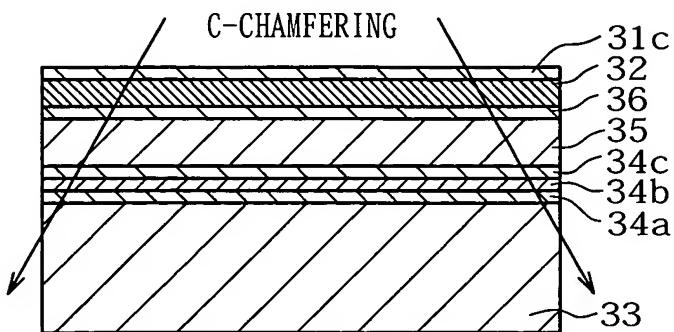
Inventor: Yamanaka Hideo

Docket No. 075834.00466

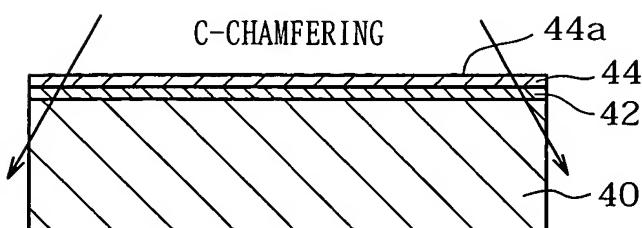
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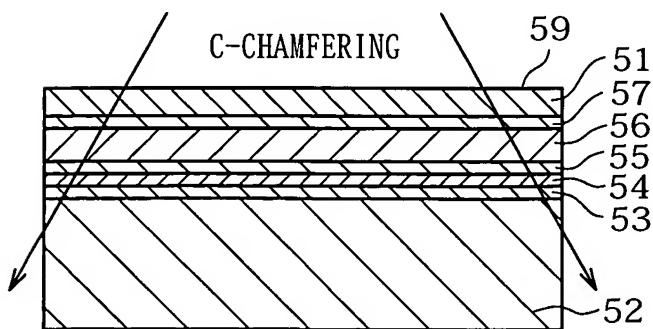
F I G. 4 2 A



F I G. 4 2 B



F I G. 4 2 C



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

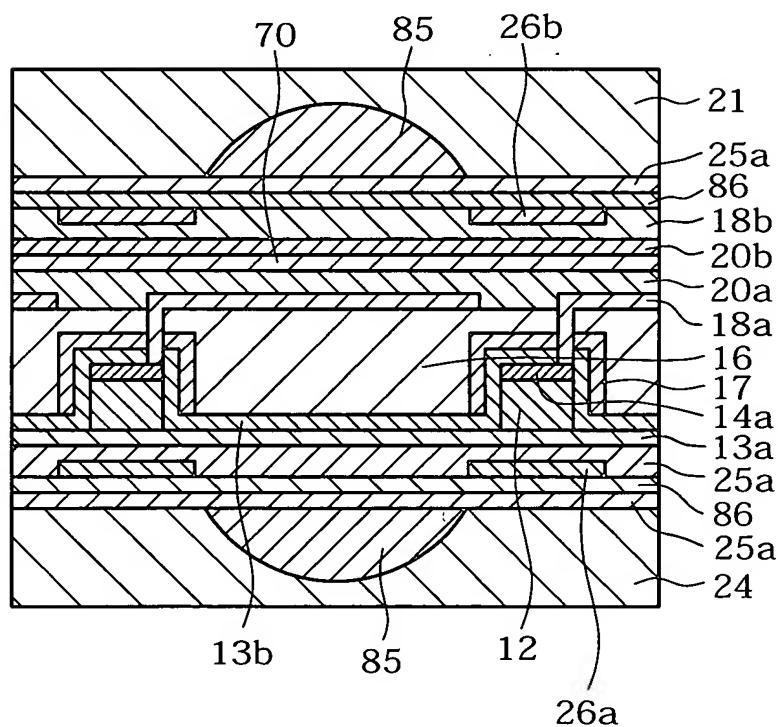
Inventor: Yamanaka Hideo

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F I G. 4 3



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

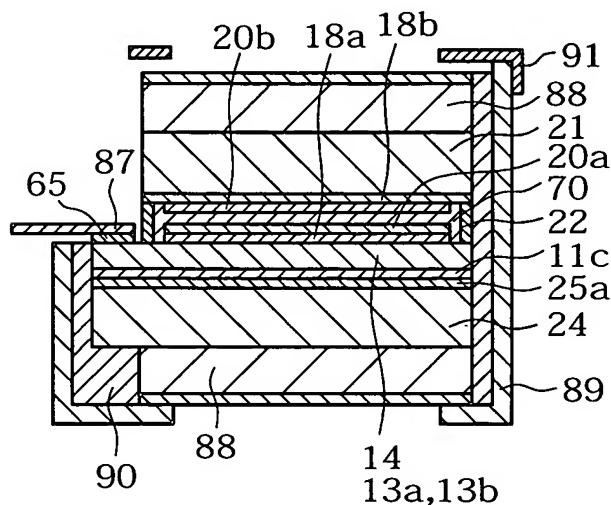
Inventor: Yamanaka Hideo

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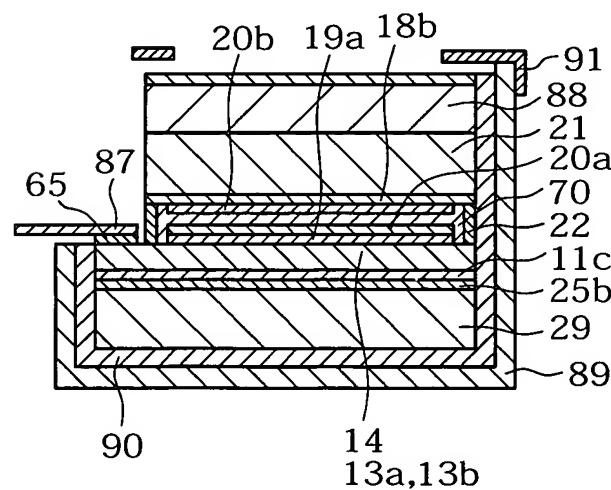
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F I G. 4 4 A



F I G. 4 4 B



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

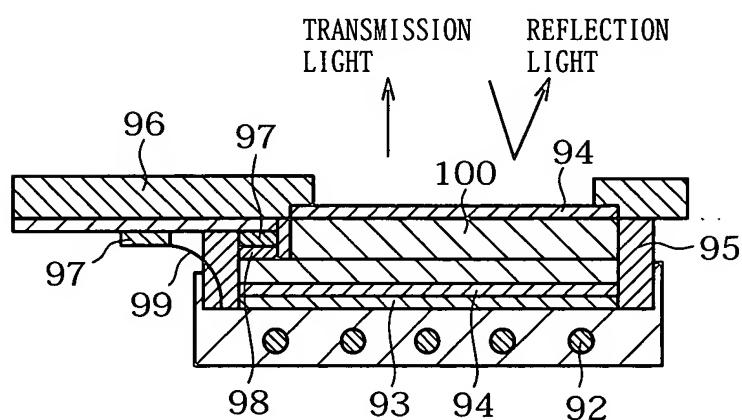
Inventor: Yamanaka Hideo

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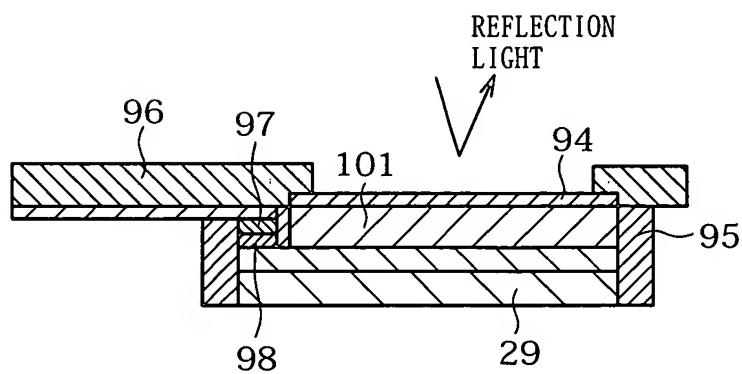
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F I G. 45 A



F I G. 45 B



MANUFACTURING PROCESS FOR ULTRA SLIM ELECTROOPTIC DISPLAY DEVICE UNIT

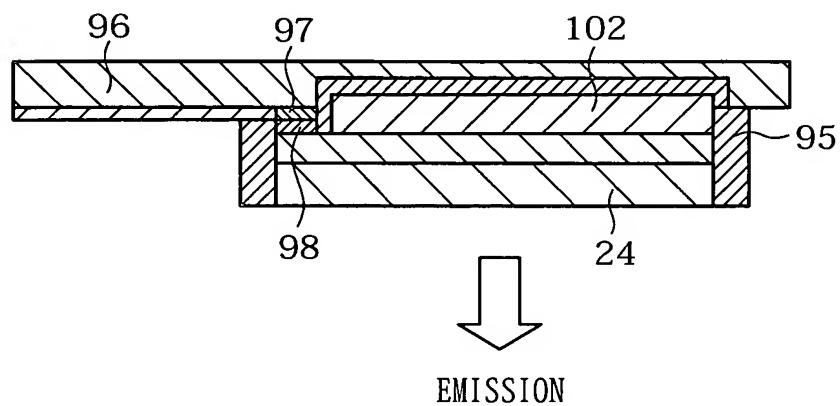
Inventor: Yamanaka Hideo

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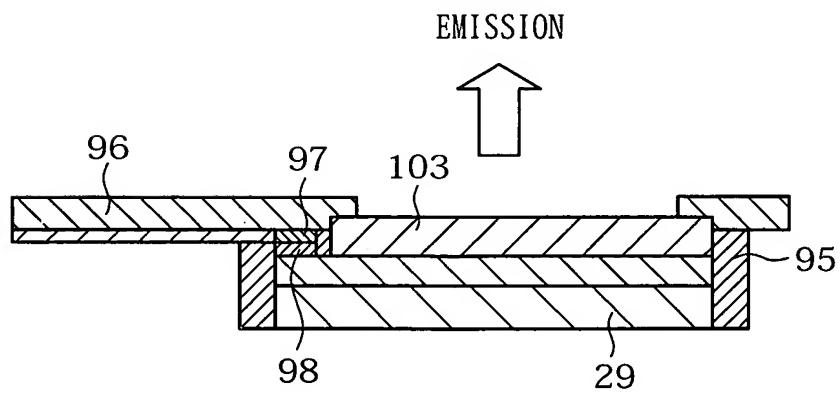
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F I G. 46 A



F I G. 46 B



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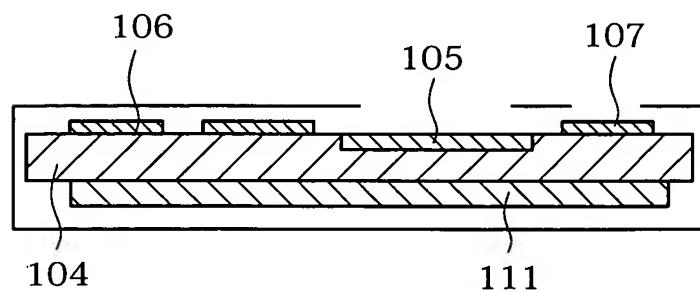
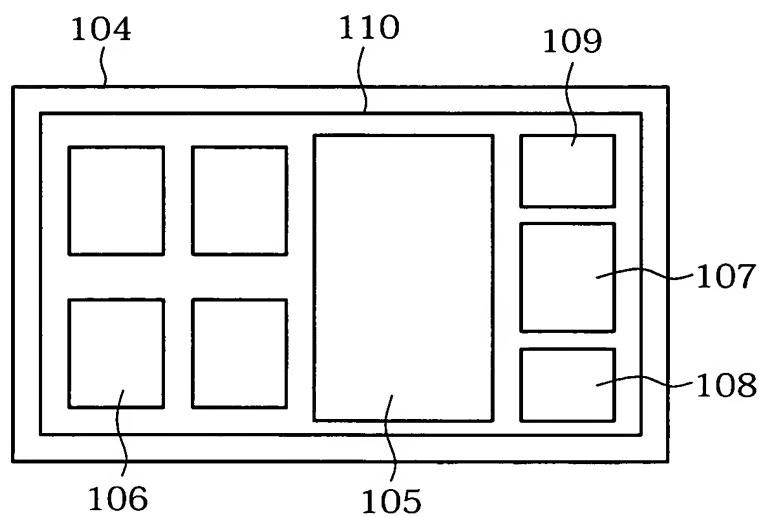
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F I G. 47



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FIG. 48A

KINDS OF ELECTROOPTIC DISPLAYS	METHOD OF LAMINATION WITH FACING SUBSTRATE	GROOVE	METHOD OF BONDING WITH A SUPPORT	CUT SECTION
REFLECTIVE LCD	FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
		↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
SINGLE FACE ASSEMBLY	↑		FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑		SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	TFT SUBSTRATE LAYER
FACE-TO-FACE ASSEMBLY	YES	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
	↑		SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE
SINGLE FACE ASSEMBLY	↑		FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑		SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUPPORT
UPPER FACE EMISSION TYPE	ORGANIC EL	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT
	—			SUBSTRATE
	—	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	—	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL SUBSTRATE
	—	—		EL/SUPPORT
TRANSMISSIVE/	FACE-TO-FACE ASSEMBLY	NONE	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
			FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT

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FIG. 48B

SEMI-TRANSMISSIVE LCD	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
SINGLE FACE ASSEMBLY	↑	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	TRANSPARENT SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TFT SUBSTRATE LAYER
FACE-TO-FACE ASSEMBLY	YES	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT
		↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE
SINGLE FACE ASSEMBLY	↑	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING SUBSTRATE
	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	-
LOWER FACE EMISSION TYPE ORGANIC EL	—	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	TRANSPARENT SUPPORT
	—	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	EL/TRANSPARENT SUPPORT
	—	YES	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	ORGANIC EL SUBSTRATE LAYER
	—	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	EL/TRANSPARENT SUPPORT
	—	—	ORGANIC EL SUBSTRATE LAYER	

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FIG. 49A

KINDS OF ELECTROOPTIC DISPLAYS	METHOD OF LAMINATION WITH A FACING SUBSTRATE	GROOVE	METHOD OF BONDING WITH A SUPPORT	CUT SECTION
REFLECTIVE LCD	FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
	↑		SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑		SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	TFT SUBSTRATE LAYER
	FACE-TO-FACE ASSEMBLY	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
	↑		SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑		SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	-
UPPER FACE EMISSION TYPE ORGANIC EL	—	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	—	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	—	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	—	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
TRANSMISSIVE/ - FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT	

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FIG. 49B

SEMI-TRANSMISSIVE LCD	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE
SINGLE FACE ASSEMBLY	↑	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	TRANSPARENT SUPPORT
	↑		SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TFT SUBSTRATE LAYER
FACE-TO-FACE ASSEMBLY	YES	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING/TRANSPARENT SUPPORT
		↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE
SINGLE FACE ASSEMBLY	↑	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING/TRANSPARENT SUPPORT
	↑		SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	-
LOWER FACE EMISSION TYPE ORGANIC EL	—		FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	ORGANIC EL / TRANSPARENT SUPPORT SUBSTRATE
	—	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	—	YES	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	ORGANIC EL / TRANSPARENT SUPPORT SUBSTRATE
	—	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER

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FIG. 50A

KINDS OF ELECTROOPTIC DISPLAYS	METHOD OF LAMINATION WITH A FACING SUBSTRATE	GROOVE	METHOD OF BONDING WITH A SUPPORT	CUT SECTION
REFLECTIVE LCD	FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
	↑		SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑		SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	TFT SUBSTRATE LAYER
	FACE-TO-FACE ASSEMBLY	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
	↑		SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑		SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	-
UPPER FACE EMISSION TYPE ORGANIC EL	—	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	—	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	—	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	—	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
TRANSMISSIVE/	FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT

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FIG. 50B

SEMI-TRANSMISSIVE LCD	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
SINGLE FACE ASSEMBLY	↑	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	TRANSPARENT SUPPORT
↑			SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TFT SUBSTRATE LAYER
FACE-TO-FACE ASSEMBLY	YES	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT
↑			SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE
SINGLE FACE ASSEMBLY	↑	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	TRANSPARENT SUPPORT
↑			SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	-
LOWER FACE EMISSION TYPE ORGANIC EL	—	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL / TRANSPARENT SUPPORT SUBSTRATE
—	—	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
—	—	YES	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	ORGANIC EL / TRANSPARENT SUPPORT SUBSTRATE
—	—	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER

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FIG. 51A

KINDS OF ELECTROOPTIC DISPLAYS	METHOD OF LAMINATION WITH A FACING SUBSTRATE	GROOVE	METHOD OF BONDING WITH A SUPPORT	CUT SECTION
REFLECTIVE LCD	FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
SINGLE FACE ASSEMBLY	↑	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	TFT SUBSTRATE LAYER
FACE-TO-FACE ASSEMBLY	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT	
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE
SINGLE FACE ASSEMBLY	↑	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	-
UPPER FACE EMISSION TYPE ORGANIC EL	—	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	—	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	—	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	—	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
TRANSMISSIVE/ FACE-TO-FACE ASSEMBLY	—	NONE	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT

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FIG. 51B

SEMI-TRANSMISSIVE LCD	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
SINGLE FACE ASSEMBLY	↑	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	TRANSPARENT SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TFT SUBSTRATE LAYER
FACE-TO-FACE ASSEMBLY	YES	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE
SINGLE FACE ASSEMBLY	↑	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING TRANSPARENT SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	-
LOWER FACE EMISSION TYPE ORGANIC EL	—	—	NONE	ORGANIC EL/TRANSPARENT SUPPORT SUBSTRATE
	—	—	↑	ORGANIC EL SUBSTRATE LAYER
	—	—	YES	ORGANIC EL SUBSTRATE LAYER

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FIG. 52A

KINDS OF ELECTROOPTIC DISPLAYS	METHOD OF LAMINATION WITH A FACING SUBSTRATE	CROOVE	METHOD OF BONDING WITH A SUPPORT	CUT SECTION
REFLECTIVE LCD	FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	TFT SUBSTRATE LAYER
	FACE-TO-FACE ASSEMBLY	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	FACING/SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
	SINGLE FACE ASSEMBLY	↑	FACE-TO-FACE ASSEMBLY OF SUPPORT	SUPPORT
	↑	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	-
UPPER FACE EMISSION TYPE ORGANIC EL	—	NONE	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL/SUPPORT SUBSTRATE
	—	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	—	YES	FACE-TO-FACE ASSEMBLY OF SUPPORT	ORGANIC EL SUBSTRATE
	—	↑	SINGLE FACE ASSEMBLY OF SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
TRANSMISSIVE / - FACE-TO-FACE ASSEMBLY	NONE	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT	CUT SECTION

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FIG. 52B

SEMI-TRANSMISSIVE LCD	↑	↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
SINGLE FACE ASSEMBLY	↑	↑	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	TRANSPARENT SUPPORT
		↑	SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TFT SUBSTRATE LAYER
FACE-TO-FACE ASSEMBLY	↑	YES	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	FACING/TRANSPARENT SUPPORT
SINGLE FACE ASSEMBLY	↑		SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	FACING SUBSTRATE/TFT SUBSTRATE LAYER
LOWER FACE EMISSION TYPE ORGANIC EL	—	NONE	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	TRANSPARENT SUPPORT
	—		SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER
	—	YES	FACE-TO-FACE ASSEMBLY OF TRANSPARENT SUPPORT	ORGANIC EL SUPPORT
	—		SINGLE FACE ASSEMBLY OF TRANSPARENT SUPPORT CHIPS	ORGANIC EL SUBSTRATE LAYER